

# EEE213 Power Electronics and Electromechanism

## 7. Power Electronic Devices

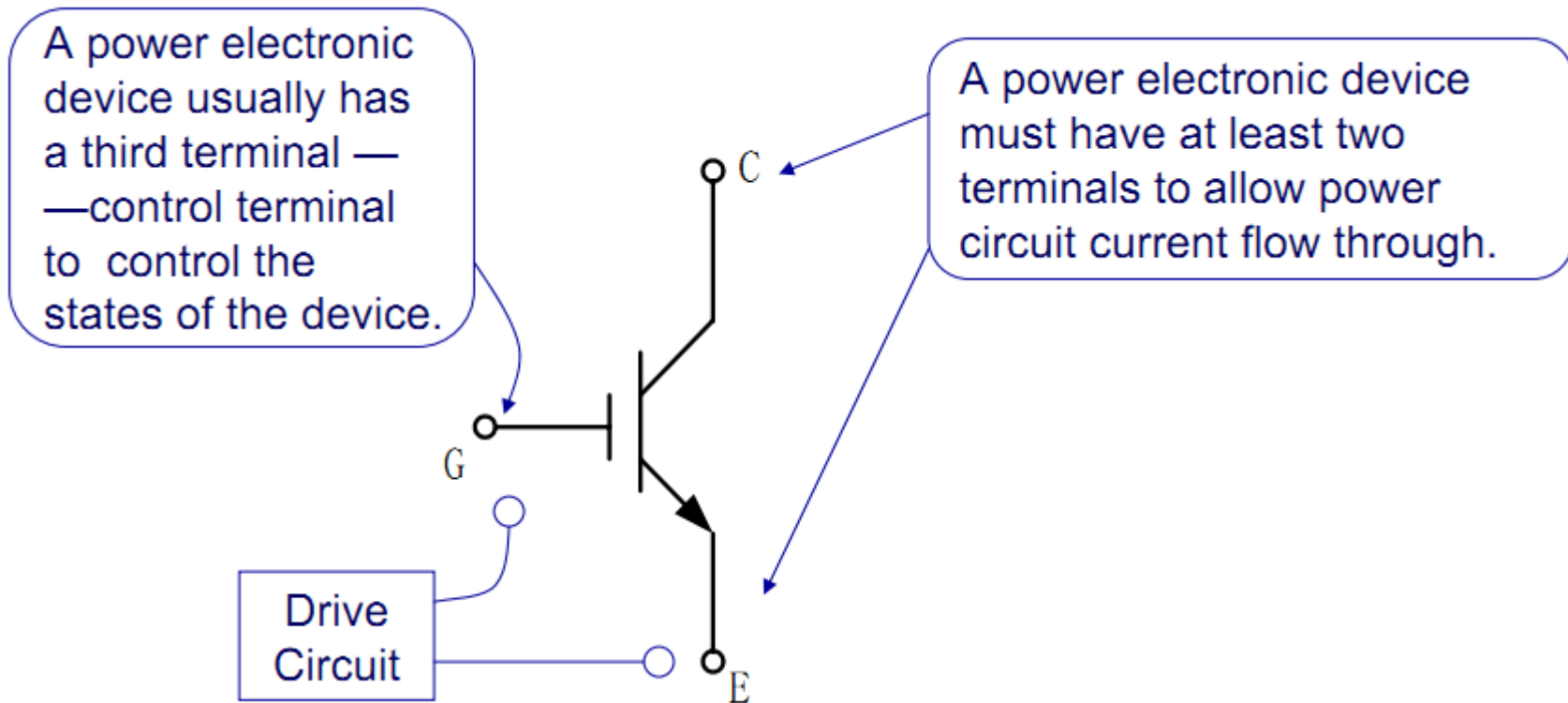
# Outline

---

- Power Electronic Devices
- Power Transistors
  - Power BJT
  - Power MOSFET
  - IGBT
- Comparison

# Power Electronic Devices

- Terminals of a controllable power electronic device



# Power semiconductor devices

---

- Power Diode – uncontrollable
- Thyristor (晶闸管)
  - SCR (Silicon Controlled Rectifier) – on controllable
  - TRIAC (Triode ac switch)
  - GTO (Gate turn-off thyristor) – on/off controllable
- Power Transistors
  - Power BJT
  - Power MOSFET
  - IGBT

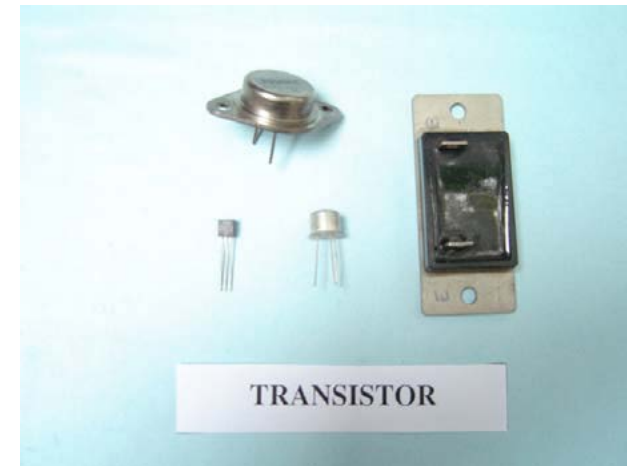
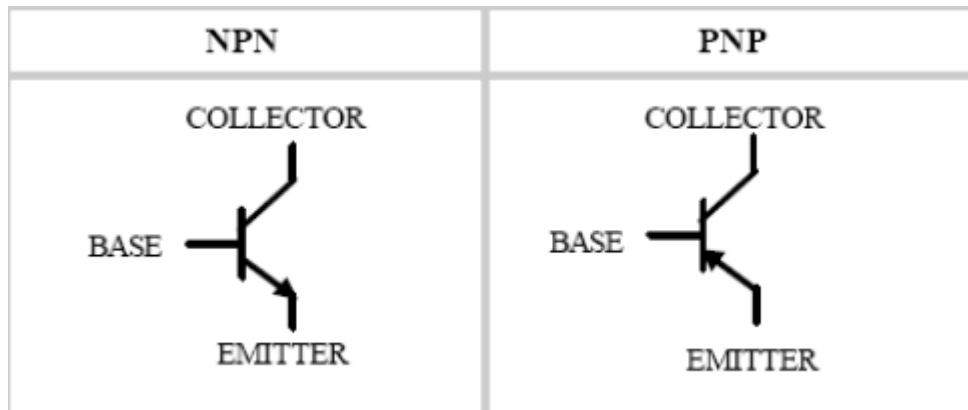
## 2. Power Transistors

---

- Features
  - Fully-controllable
  - High frequency
  - IC fabrication technology
- Applications
  - From 1980s
  - GTR and GTO are seldom in use today
  - IGBT and power MOSFET are the two major power semiconductor devices nowadays

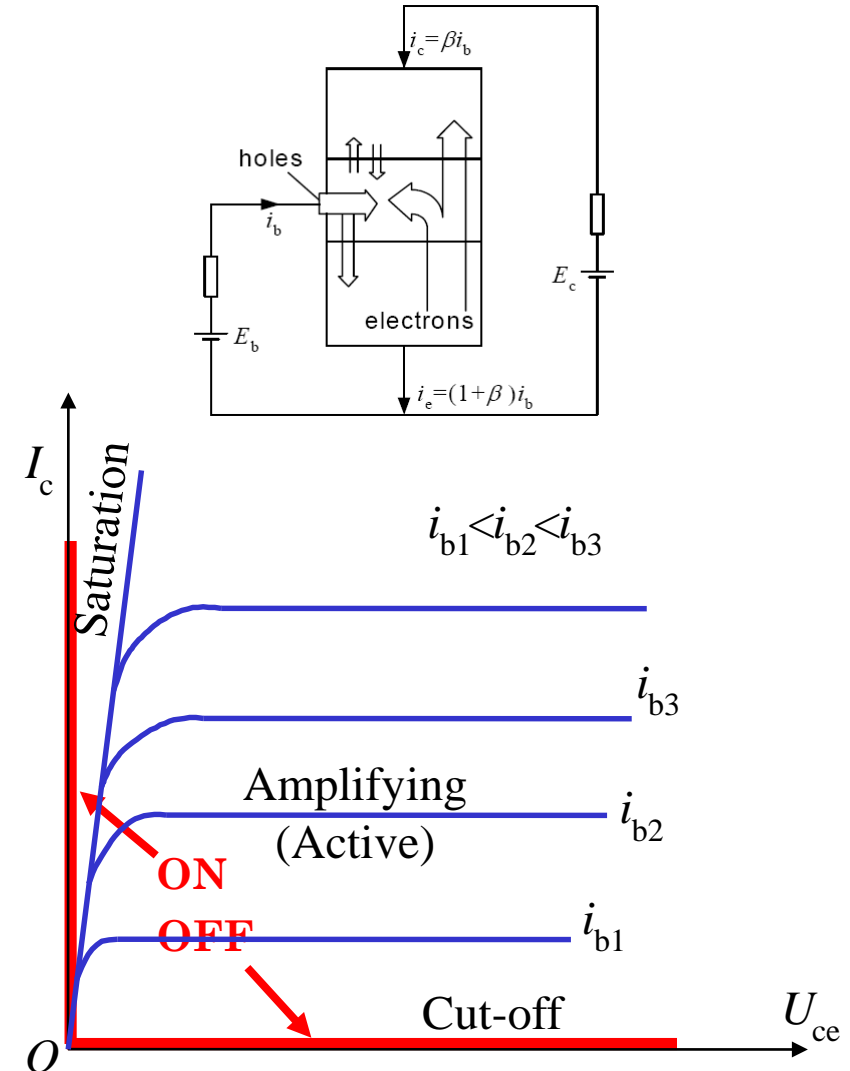
## 2.1 Power BJT

- Three-terminal devices with NPN or PNP type
- The terminals c-e are used as a fully controllable (one-way) switch controlled by the current signal through b-e
- Also called GTR (Giant Transistor)



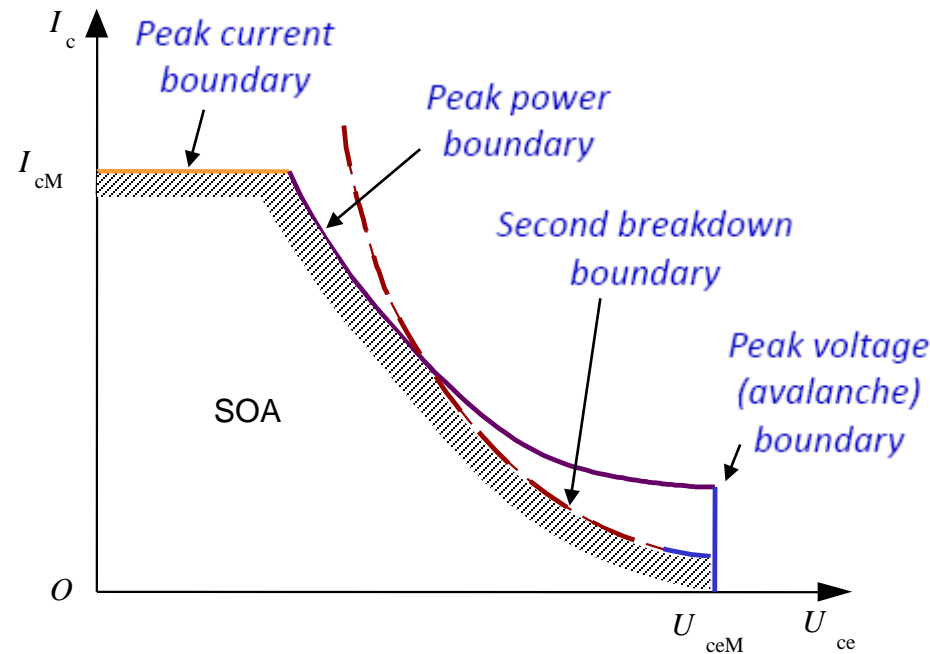
# BJT I-V Characteristics

- Comparing with information-processing BJT
  - Basic operation principles are the same
  - Special features: higher voltage withstand, larger current, better switching characteristics
  - Common-emitter connection
  - Operating in ON-OFF states



# Breakdown and SOA

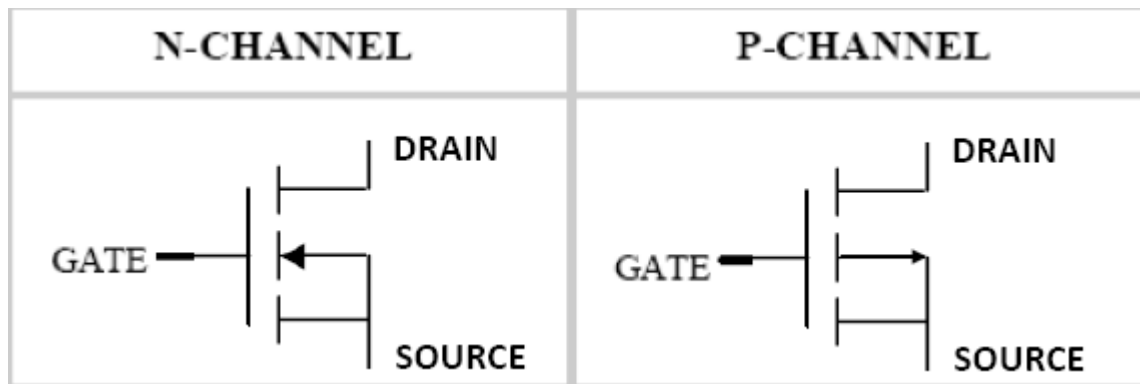
- Avalanche breakdown
  - the 1<sup>st</sup> breakdown
- The 2<sup>nd</sup> breakdown
  - A destructive phenomenon
  - Due to the current flow to a small portion of the base, producing localized hot spots
  - A localized thermal runaway
  - Cause the permanent damage of the device
- Safe operating area (SOA)





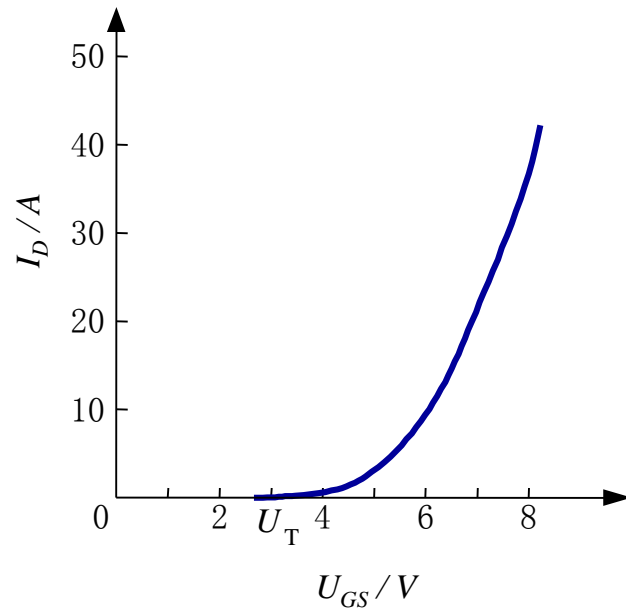
## 2.2 Power MOSFET

- Three-terminal devices with a P or N channel
- Relatively high input impedance
- The switch between d-s is fully controlled by a voltage signal between g-s.

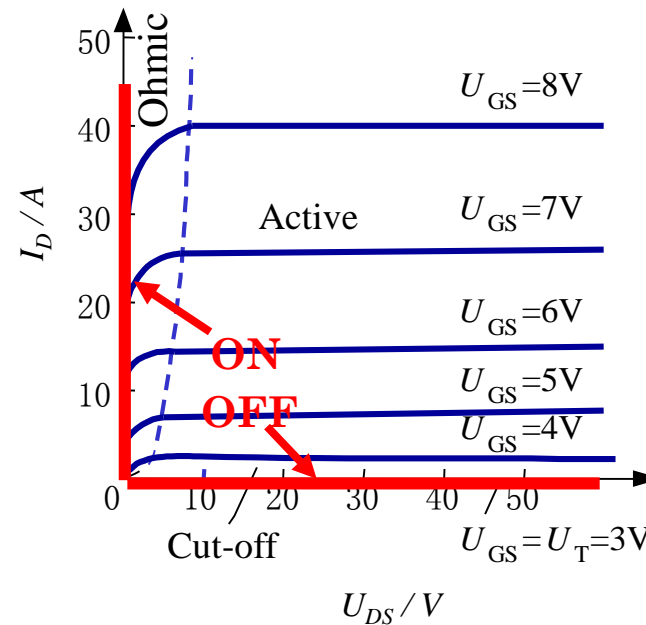


# MOSFET I-V Characteristics

- Operating in switching mode: On-Off
- No 2nd-breakdown problem

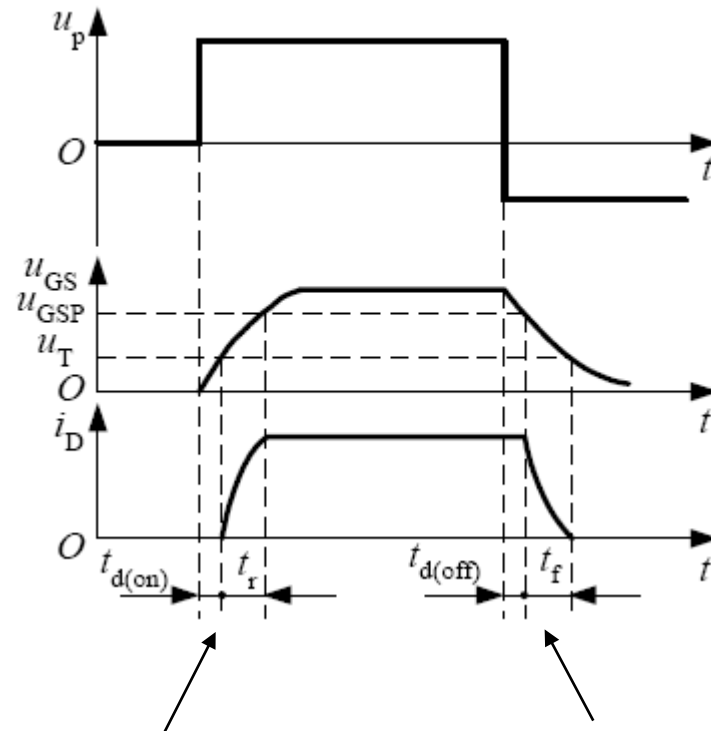
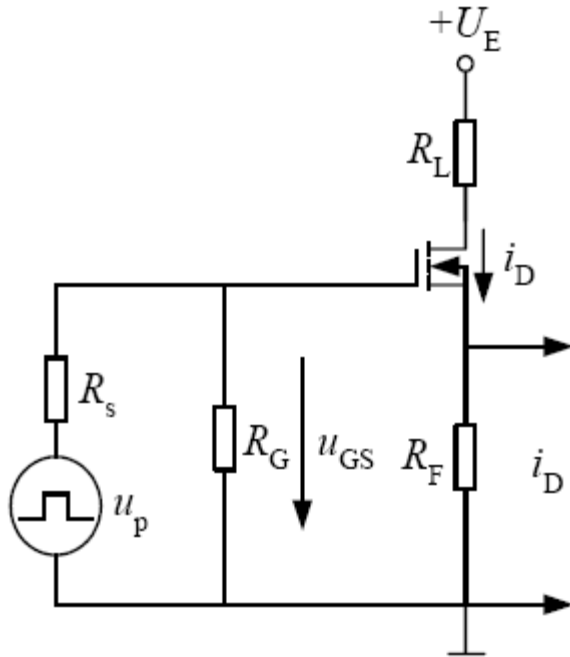


Transfer



Output

# Switching characteristics



✦ Turn-on transient

- Turn-on delay time  $t_{d(on)}$
- Rise time  $t_r$

✦ Turn-off transient

- Turn-off delay time  $t_{d(off)}$
- Falling time  $t_f$

# Features and applications

---

- Very fast switching speed, high operating frequency (could be hundreds of kHz)
- High input impedance; voltage controlled device; easy to drive
- No 2nd-breakdown problem => wider SOA than BJT
- Easy to use in parallel
- Conduction loss of MOSFET is larger than that of BJT due to a larger voltage drop for high-voltage applications
- On-resistance increases rapidly with rated blocking voltage
  - Usually used at voltages less than 500V and power less than 10kW
  - 1000V devices are available, but are useful only at low power levels (100W)

## 2.3 IGBT

- A hybrid MOS-gated bipolar transistor
- Combination of power transistor and MOSFET

**GTR:** 😊 low conduction losses (especially at larger blocking voltages),

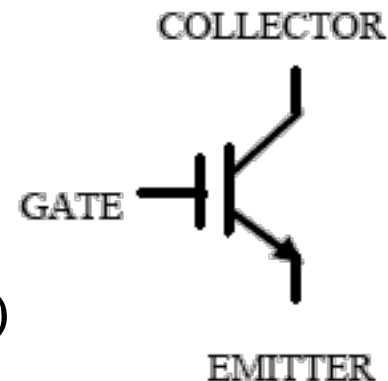
😞 longer switching times, current-driven

**MOSFET:** 😊 faster switching speed, easy to drive (voltage-driven),

😞 larger conduction losses (especially for higher blocking voltages)

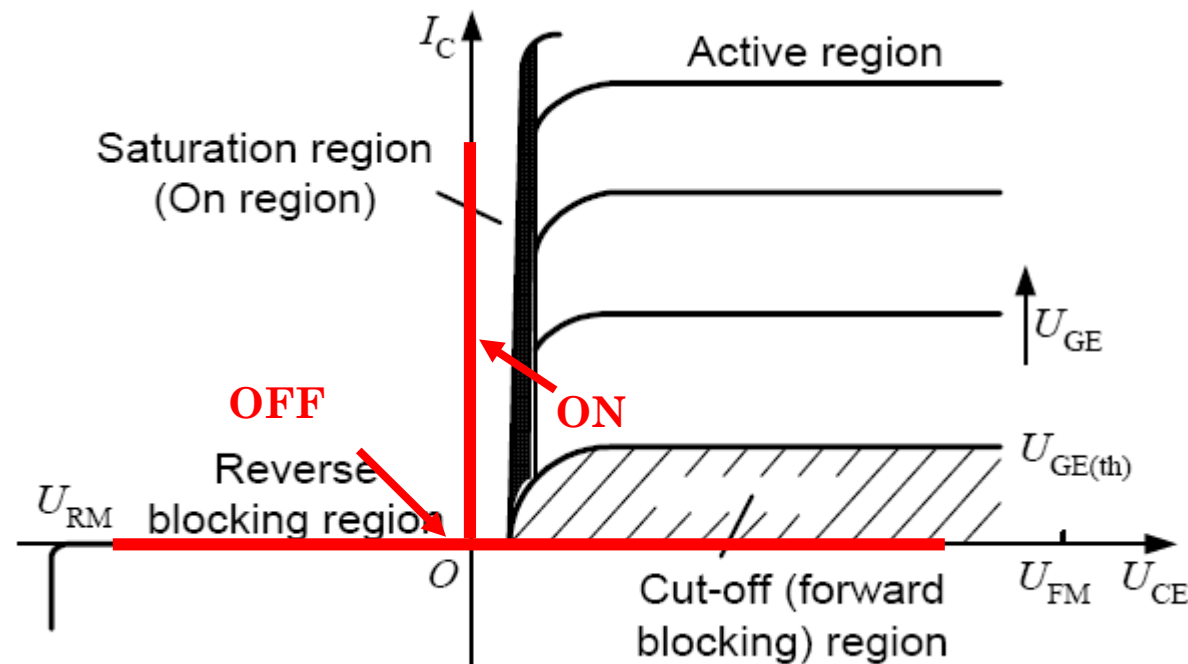
IGBT

- Features
- Low conduction loss (BJT)
  - High-speed turn-on (MOSFET)
  - Low-power, easy drive (MOSFET)



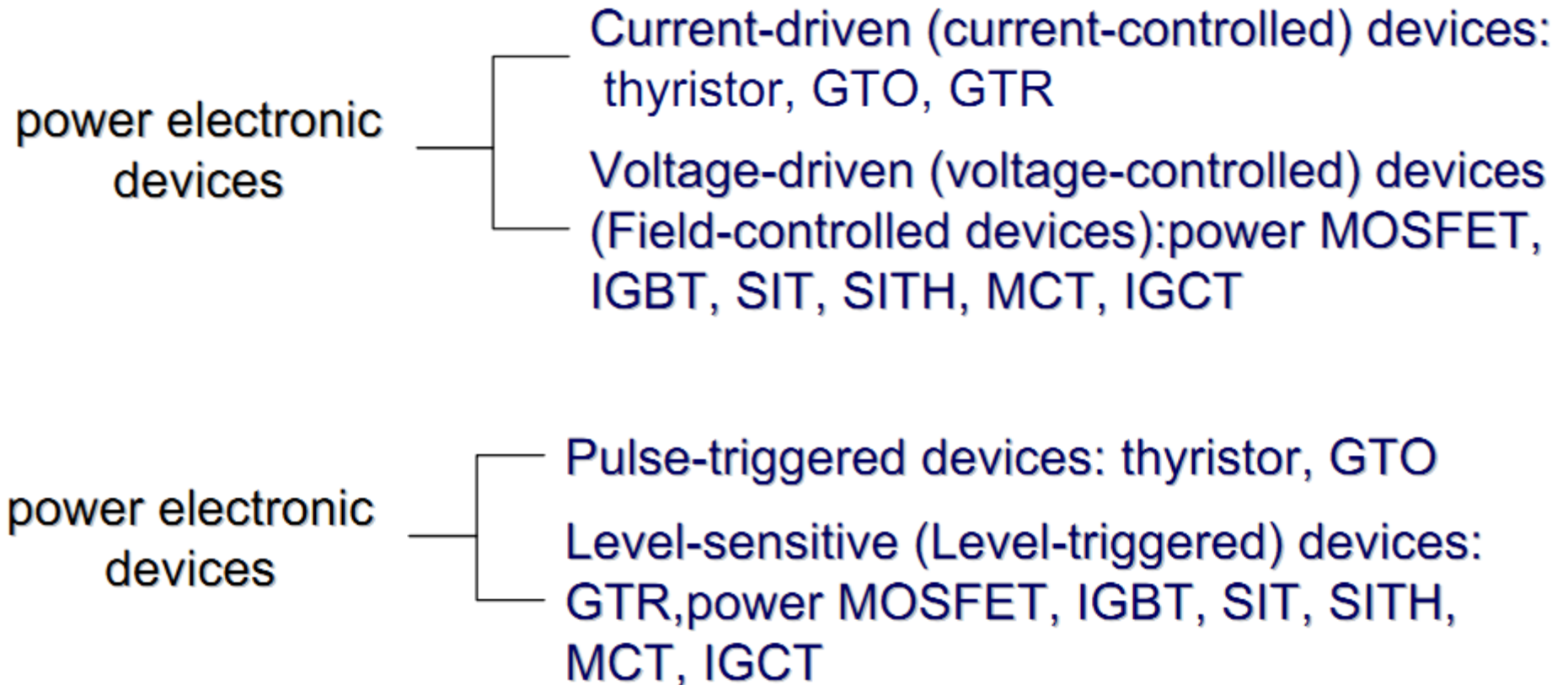
# IGBT I-V Characteristics

- On-state losses are much smaller than those of a power MOSFET
- Faster than GTR, but slower than power MOSFET
- Easy to drive —similar to power MOSFET

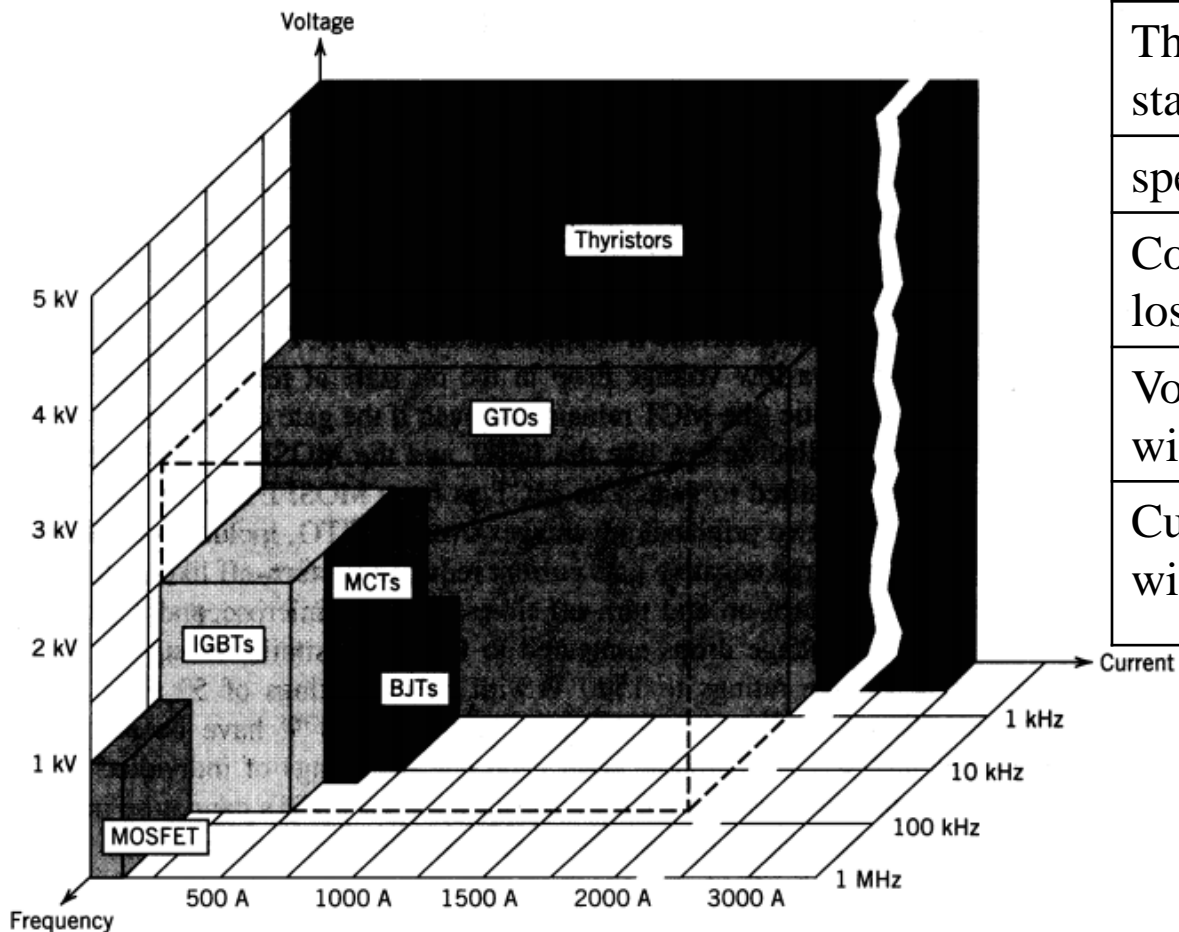


# Review of the classifications

---



# Comparison of power semiconductor devices



	GTR	MOSFET	IGBT
Driven	I	V	V
Input impedance	low	high	high
Thermal stability	Bad(2 <sup>nd</sup> BR)	Good (no 2 <sup>nd</sup> )	Good (no 2 <sup>nd</sup> )
speed	low	high	medium
Conduction loss	low	high	low
Voltage withstand	high	low	high
Current withstand	high	low	high